

ABSTRACT

CORE MATERIAL, ELECTRONIC COMPONENT AND
METHOD FOR FORMING BUMP ELECTRODE

A core material has a core; a solder layer provided outside the core and being a solder alloy containing Sn and at least any one element of Ag, Cu, Sb, Ni, Co, Ge, Ga, Fe, Al, In, Cd, Zn, Pb, Au, P, S, Si, Ti, Mg, Pd, and Pt; and a Sn layer provided outside the solder layer. The solder layer has a thickness of 1 μm or more on one side. The Sn layer has a thickness of 0.1 μm or more on one side. A thickness of the Sn layer is 0.215% or more and 36% or less of the thickness of the solder layer.

Fig. 1